



Title of Change:	Change in Power Metal plating and Bondwires from Cu to Au for NCV7707DQBR2G.	
Proposed Changed Material First Ship Date:	31 March 2019	
Current Material Last Order Date:	31 December 2017 Orders received after the Current Material Last Order Date expiration are to be considered as orders for new changed material as described in this PCN. Orders for current (unchanged) material after this date will be per mutual agreement and current material inventory availability.	
Current Material Last Delivery Date:	30 June 2018 The Current Material Last Delivery Date may be subject to change based on build and depletion of the current (unchanged) material inventory.	
Product Category:	Active components – Integrated circuits	
Contact information:	Contact your local ON Semiconductor Sales Office or <Catherine.Dekeukeleire@onsemi.com>	
Samples:	Contact your local ON Semiconductor Sales Office to place sample order. Sample requests are to be submitted no later than 45 days after publication of this change notification.	
Sample Availability Date:	1 January 2018	
PPAP Availability Date:	12 January 2018	
Additional Reliability Data:	Reliability Test result is same between BEFORE and AFTER. Full reliability report for the Au wire and Au power metal material is available upon request.	
Type of Notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 12 months prior to implementation of the change or earlier upon customer approval. ON Semiconductor will consider this proposed change and it’s conditions acceptable, unless an inquiry is made in writing within 45 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>.	
Change Category:	Type of Change	
Process – Assembly	Cu Bond wires to Au Bond wires	
Design	Design Change in Active Elements	
Process – Wafer Production	New / change of metallization (specifically chip frontside)". Change of Cu Power Metal to Au Power Metal	
Description and Purpose:  Change in Power Metal plating and Bondwires from Cu to Au for NCV7707DQBR2G.		
Reason / Motivation for Change:	<ul style="list-style-type: none"><li>- Change benefits for customer: CuPM line is EOL’ed at CB LH site</li><li>- Risk for late release for customer: Delivery of NCV7707DQBR2G after bridge inventory runs out.</li></ul>	
Anticipated impact on fit, form, function, reliability, product safety or manufacturability	The device has been qualified and validated based on the same Product Specification. The device has successfully passed the qualification tests. Potential impacts can be identified, but due to testing performed by ON Semiconductor in relation to the PCN, associated risks are verified and excluded.  No anticipated impacts.	
Sites Affected:	ON Semiconductor Sites: All Sites	External Foundry/Subcon Sites: Chipbond
Marking of Parts/ Traceability of Change:	Affected products will be identified by datecode.	

**Reliability Data Summary:**

Reliability Test result is same between BEFORE and AFTER. Full reliability report for the Au wire and Au power metal material is available upon request.

**Electrical Characteristic Summary:**

Electrical characteristics are not impacted. Electrical results are the same BEFORE and AFTER the change.

**List of Affected Standard Parts:**

Current Part Number	New Part Number	Qualification Vehicle
NCV7707DQBR2G	NCV7707DQBR2G	NCV7707DQBR2G



Appendix A: Changed Products

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Product	Customer Part Number	New Part Number	Qualification Vehicle
NCV7707DQBR2G		NA	NA